

## 21V, 2A/2.5A, 340KHz Synchronous Step-Down DC/DC Converter

### Description

The FR9886C is a synchronous step-down DC/DC converter that provides wide 4.5V to 21V input voltage range. There are two packages (SOP-8 & SOP-8(EP)) to support 2A/2.5A continuous output current.

The FR9886C fault protection includes cycle-by-cycle current limit, input UVLO, output over voltage protection and thermal shutdown. Besides, adjustable soft-start function prevents inrush current at turn-on. This device uses current mode control scheme which provides fast transient response. In shutdown mode, the supply current is less than 1 $\mu$ A.

The FR9886C is available in SOP-8 and SOP-8 exposed pad packages. It is RoHS compliant and 100% lead (Pb) free.

### Features

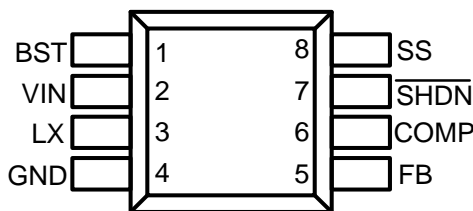
- High Efficiency Synchronous Buck Converter with Low  $I_{SD}$  (<1 $\mu$ A)
- Low  $R_{ds(on)}$  Integrated Power MOSFET
- Wide Input Voltage Range: 4.5V to 21V
- Adjustable Output Voltage from 0.925V to 17.85V
- 2A Output Current (Package: SOP-8)
- 2.5A Output Current (Package: SOP-8(EP))
- Fixed 340KHz Switching Frequency
- Current Mode Operation
- Adjustable Soft-Start
- Cycle-by-Cycle Current Limit
- Input Under Voltage Lockout
- Over-Temperature Protection with Auto Recovery
- SOP-8 and SOP-8 Exposed Pad Packages

### Applications

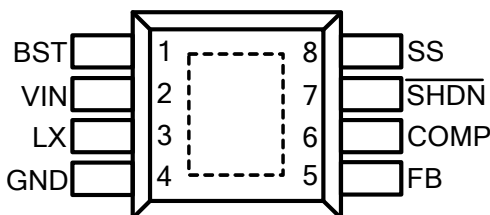
- Set-Top-Box
- DVD, LCD Display
- OLPC, Netbook
- Distributed Power System
- Datacom, XDSL

### Pin Assignments

#### SO Package (SOP-8)



#### SP Package (SOP-8 Exposed Pad)



### Ordering Information

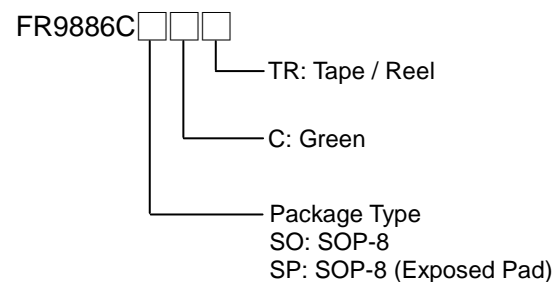


Figure 1. Pin Assignment of FR9886C

**Typical Application Circuit**

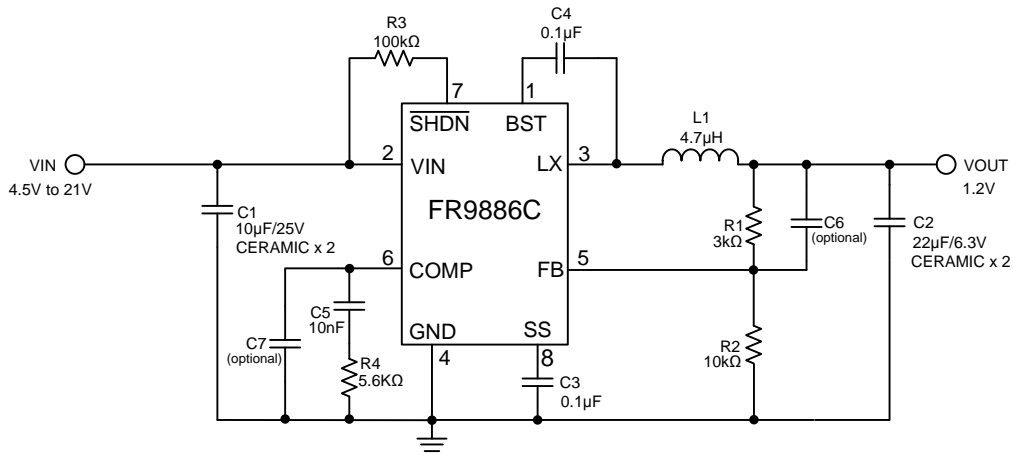


Figure 2.  $C_{IN}/C_{OUT}$  use Ceramic Capacitors Application Circuit

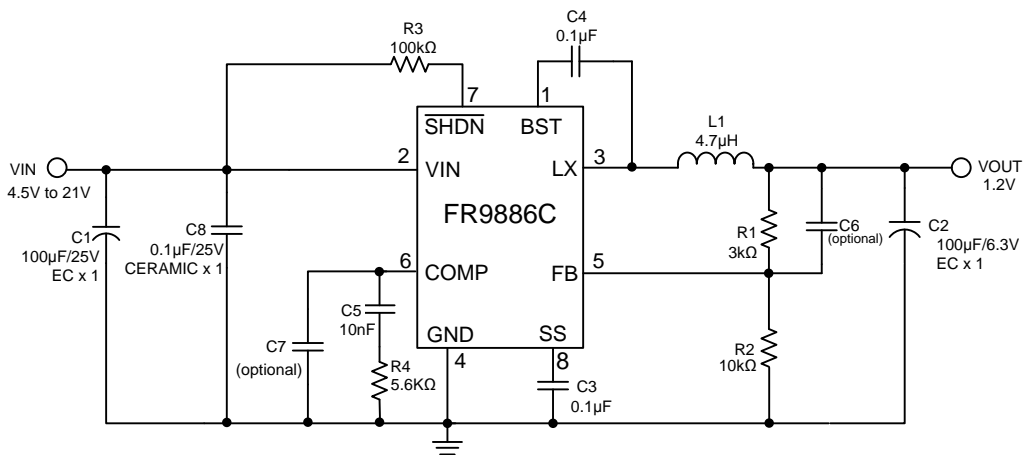


Figure 3.  $C_{IN}/C_{OUT}$  use Electrolytic Capacitors Application Circuit

## Functional Pin Description

Pin Name	Pin No.	I/O	Pin Function
<b>FB</b>	<b>5</b>	<b>I</b>	Voltage Feedback Input Pin. Connect FB and $V_{OUT}$ with a resistive voltage divider. This IC senses feedback voltage via FB and regulates it at 0.925V.
<b>VIN</b>	<b>2</b>	<b>I</b>	Power Supply Input Pin. Drive this pin by 4.5V to 21V voltage to power on the chip.
<b><math>\overline{\text{SHDN}}</math></b>	<b>7</b>	<b>I</b>	Enable Input Pin. This pin provides a digital control to turn the converter on or off. Connect VIN with a 100K $\Omega$ resistor for self-startup.
<b>GND</b>	<b>4</b>	<b>I</b>	Ground Pin. Connect this pin to exposed pad.
<b>LX</b>	<b>3</b>	<b>O</b>	Power Switching Output. It is the output pin of internal high side NMOS which is the switch to supply power.
<b>SS</b>	<b>8</b>	<b>O</b>	Soft-Start Pin. This pin controls the soft-start period. Connect a capacitor from SS to GND to set the soft start period.
<b>BST</b>	<b>1</b>	<b>O</b>	High Side Gate Drive Boost Pin. A capacitor rating between 10nF to 0.1 $\mu\text{F}$ must be connected from this pin to LX. It can boost the gate drive to fully turn on the internal high side NMOS.
<b>COMP</b>	<b>6</b>	<b>O</b>	Compensation Pin. This pin is used to compensate the regulation control loop. Connect a series RC network from COMP pin to GND.

## Block Diagram

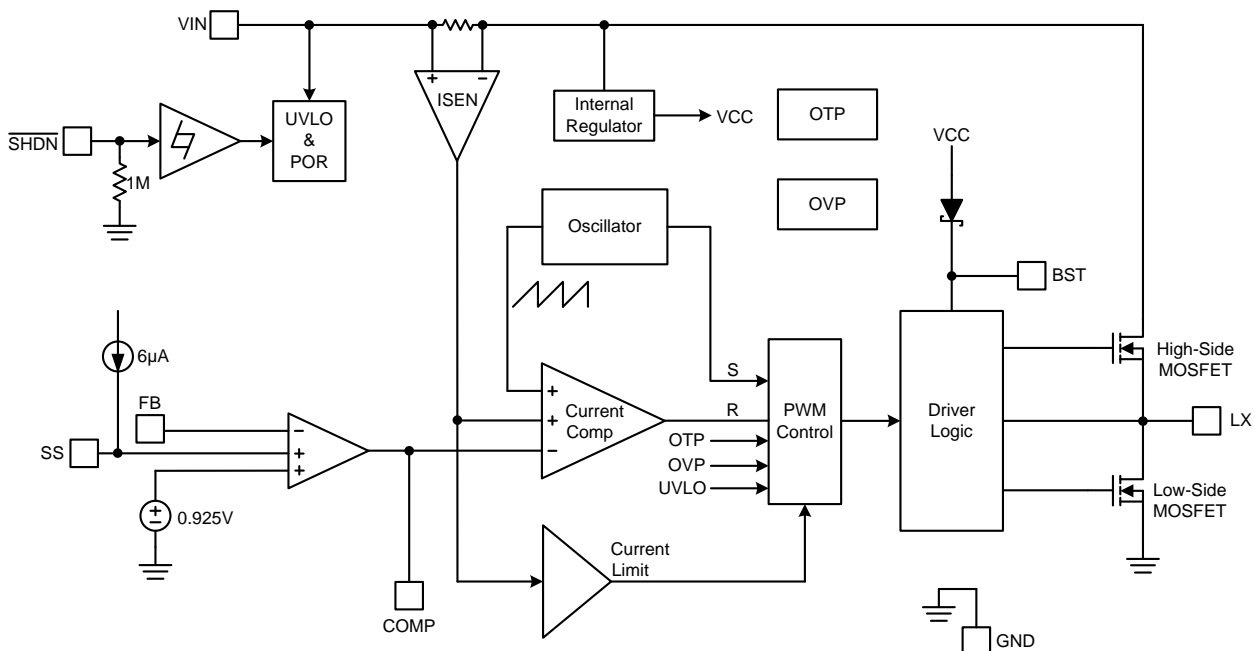


Figure 4. Block Diagram of FR9886C

## Absolute Maximum Ratings (Note1)

• Supply Voltage $V_{IN}$ .....	-0.3V to +23V
• Enable Voltage $V_{\overline{SHDN}}$ .....	-0.3V to +23V
• LX Voltage $V_{LX}$ .....	-1V to $V_{IN}+0.3V$
• BST Voltage $V_{BST}$ .....	$V_{LX}-0.3V$ to $V_{LX}+6V$
• All Other Pins Voltage .....	-0.3V to +6V
• Maximum Junction Temperature ( $T_J$ ) .....	+150°C
• Storage Temperature ( $T_S$ ) .....	-65°C to +150°C
• Lead Temperature (Soldering, 10sec.) .....	+260°C
• Power Dissipation @ $T_A=25^\circ C$ , ( $P_D$ ) (Note2)	
SOP-8 .....	1.39W
SOP-8 (Exposed Pad) .....	2.08W
• Package Thermal Resistance, ( $\theta_{JA}$ )	
SOP-8 .....	90°C/W
SOP-8 (Exposed Pad) .....	60°C/W
• Package Thermal Resistance, ( $\theta_{JC}$ )	
SOP-8 .....	39°C/W
SOP-8 (Exposed Pad) .....	15°C/W

Note 1 : Stresses beyond this listed under "Absolute Maximum Ratings" may cause permanent damage to the device.

Note 2 : PCB heat sink copper area = 10mm<sup>2</sup>.

## Recommended Operating Conditions

• Supply Voltage $V_{IN}$ .....	+4.5V to +21V
• Enable Voltage $V_{\overline{SHDN}}$ .....	0V to $V_{IN}$
• Operation Temperature Range .....	-40°C to +85°C

## Electrical Characteristics

( $V_{IN}=12V$ ,  $T_A=25^{\circ}C$ , unless otherwise specified.)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
$V_{IN}$ Input Supply Voltage	$V_{IN}$		4.5		21	V
$V_{IN}$ Quiescent Current	$I_{DDQ}$	$V_{\overline{SHDN}}=1.8V$ , $V_{FB}=1.0V$		2		mA
$V_{IN}$ Shutdown Supply Current	$I_{SD}$	$V_{\overline{SHDN}}=0V$			1	$\mu A$
Feedback Voltage	$V_{FB}$	$4.5V \leq V_{IN} \leq 21V$	0.9	0.925	0.95	V
Feedback OVP Threshold Voltage	$V_{OVP}$			1.5		V
High-Side MOSFET $R_{DS(ON)}$ (Note3)	$R_{DS(ON)}$	SOP-8		130		m $\Omega$
		SOP-8 (EP)		120		
Low-Side MOSFET $R_{DS(ON)}$ (Note3)	$R_{DS(ON)}$			110		m $\Omega$
High-Side MOSFET Leakage Current	$I_{LX(leak)}$	$V_{\overline{SHDN}}=0V$ , $V_{LX}=0V$			10	$\mu A$
High-Side MOSFET Current Limit (Note3)	$I_{LIMIT(HS)}$	Minimum Duty	SOP-8	2.8	4	A
			SOP-8 (EP)	3.1	4.5	
Low-Side MOSFET Current Limit (Note3)	$I_{LIMIT(LS)}$	From Drain to Source		1.5		A
Current sense to COMP Transconductance (Note3)				3.5		A/V
Error Amplifier Transconductance (Note3)		$\Delta I_{COMP} = \pm 10\mu A$		1600		$\mu A/V$
Error Amplifier Voltage Gain (Note3)				400		V/V
Oscillation frequency	$F_{OSC}$		290	340	420	KHz
Short Circuit Oscillation Frequency	$F_{OSC(short)}$	$V_{FB}=0V$		110		KHz
Maximum Duty Cycle	$D_{MAX}$	$V_{FB}=0.8V$		90		%
Minimum On Time (Note3)	$T_{MIN}$			100		ns
Input UVLO Threshold	$V_{UVLO(Vth)}$	$V_{IN}$ Rising		4.3		V
Under Voltage Lockout Threshold Hysteresis	$V_{UVLO(HYS)}$			400		mV
Soft-Start Current	$I_{SS}$	$V_{SS}=0V$		6		$\mu A$
Soft-Start Period	$T_{SS}$	$C_{SS}=0.1\mu F$		15		ms
$\overline{SHDN}$ Input Low Voltage	$V_{\overline{SHDN}(L)}$				0.4	V
$\overline{SHDN}$ Input High Voltage	$V_{\overline{SHDN}(H)}$		2			V
$\overline{SHDN}$ Input Current	$I_{\overline{SHDN}}$	$V_{\overline{SHDN}}=2V$		2		$\mu A$
Thermal Shutdown Threshold (Note3)	$T_{SD}$			170		$^{\circ}C$

Note 3 : Not production tested.

**Typical Performance Curves**

$V_{IN}=12V$ ,  $V_{OUT}=3.3V$ ,  $C1=10\mu F \times 2$ ,  $C2=22\mu F \times 2$ ,  $L1=10\mu H$ ,  $T_A=+25^\circ C$ , unless otherwise noted.

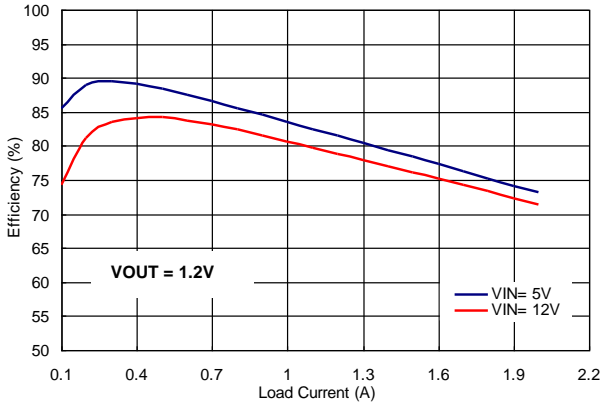


Figure 5. Efficiency vs. Loading (SOP-8)

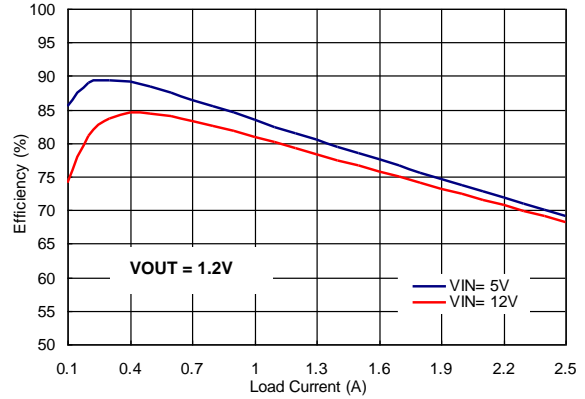


Figure 6. Efficiency vs. Loading (SOP-8 Exposed Pad)

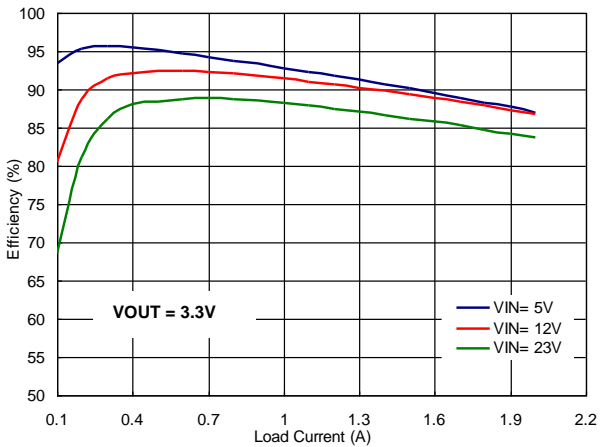


Figure 7. Efficiency vs. Loading (SOP-8)

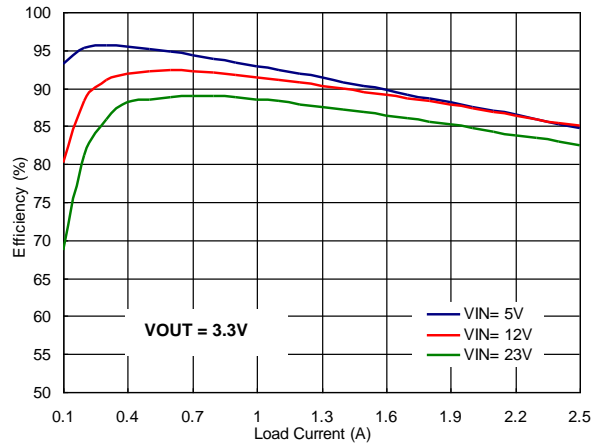


Figure 8. Efficiency vs. Loading (SOP-8 Exposed Pad)

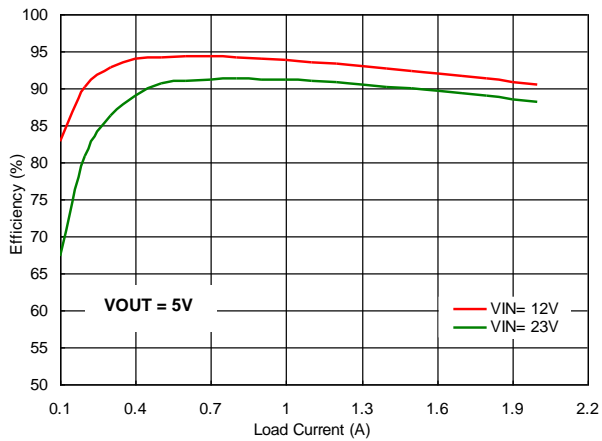


Figure 9. Efficiency vs. Loading (SOP-8)

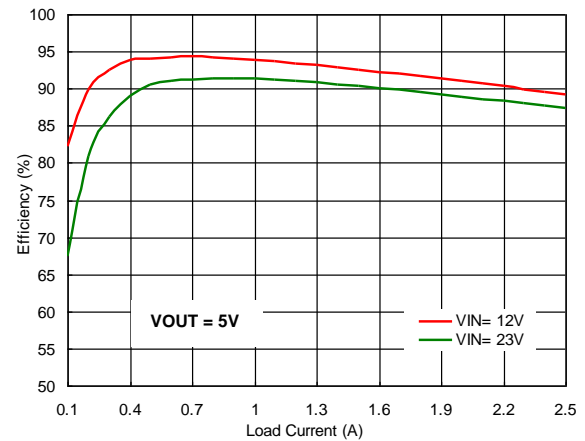


Figure 10. Efficiency vs. Loading (SOP-8 Exposed Pad)

**Typical Performance Curves (Continued)**

$V_{IN}=12V$ ,  $V_{OUT}=3.3V$ ,  $C1=10\mu F \times 2$ ,  $C2=22\mu F \times 2$ ,  $L1=10\mu H$ ,  $T_A=+25^\circ C$ , unless otherwise noted.

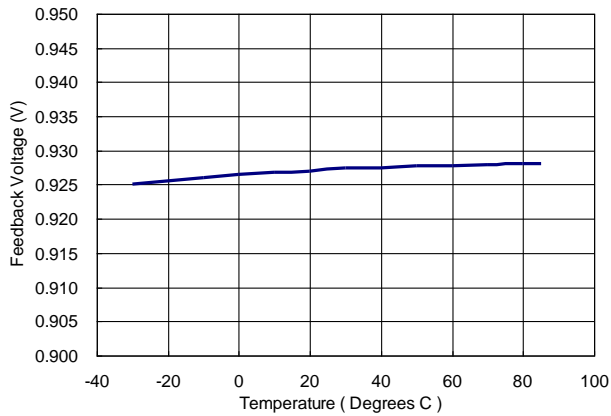


Figure 11. Feedback Voltage vs. Temperature

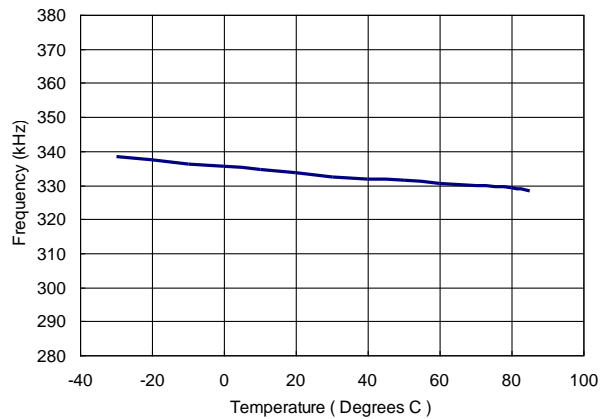


Figure 12. Frequency vs. Temperature

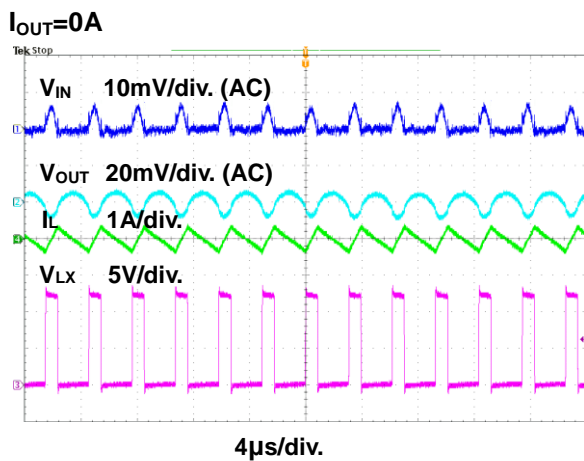


Figure 13. DC Ripple Waveform

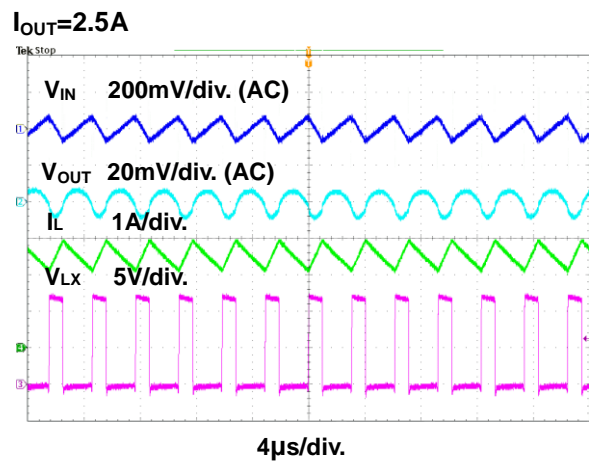


Figure 14. DC Ripple Waveform

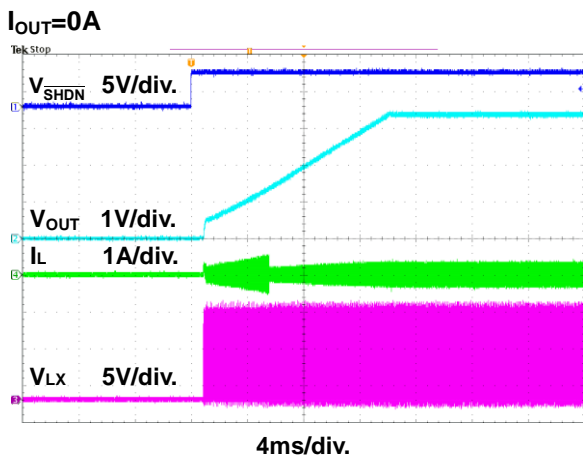


Figure 15. Startup Through  $\overline{SHDN}$  Waveform

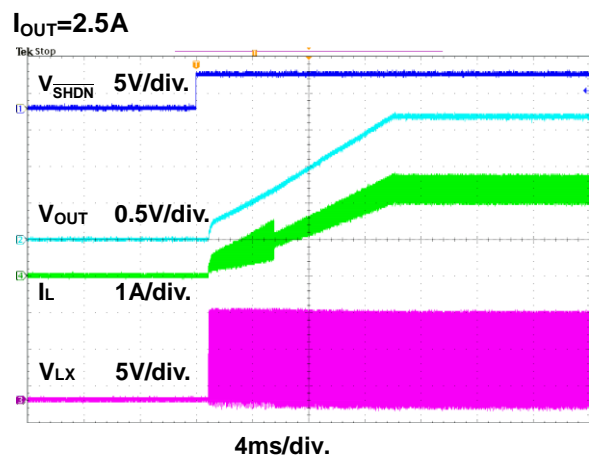


Figure 16. Startup Through  $\overline{SHDN}$  Waveform

**Typical Performance Curves (Continued)**

$V_{IN}=12V$ ,  $V_{OUT}=3.3V$ ,  $C1=10\mu F \times 2$ ,  $C2=22\mu F \times 2$ ,  $L1=10\mu H$ ,  $T_A=+25^\circ C$ , unless otherwise noted.

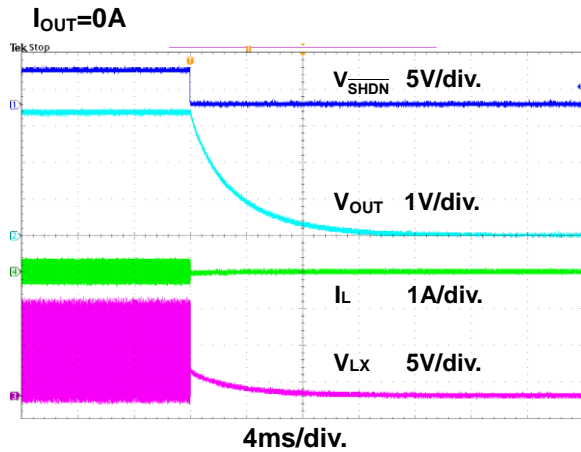


Figure 17. Shutdown Through  $\overline{SHDN}$  Waveform

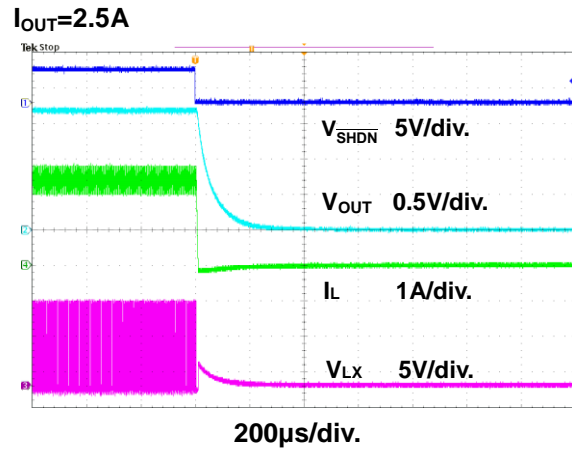


Figure 18. Shutdown Through  $\overline{SHDN}$  Waveform

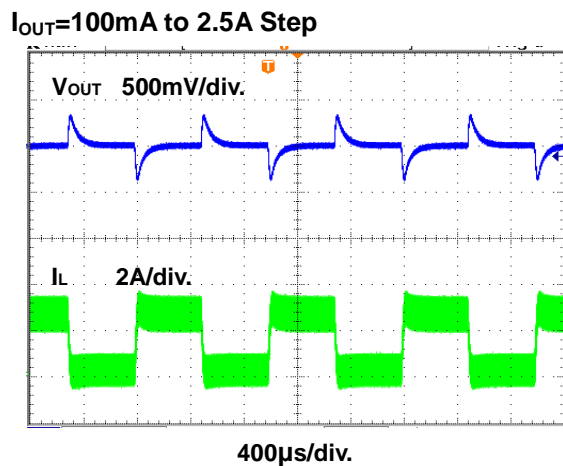


Figure 19. Load Transient Waveform

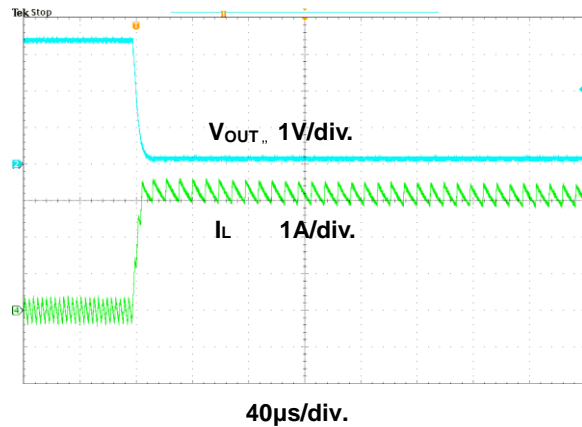


Figure 20. Short Circuit Test



## Function Description

The FR9886C is a high efficiency and constant frequency current mode step-down synchronous DC/DC converter. It has integrated high-side (130mΩ, typ) and low-side (110mΩ, typ) power switches. There are two packages (SOP-8 & SOP-8(EP)) to support 2A/2.5A continuous output current. It regulates input voltage from 4.5V to 21V and down to an output voltage as low as 0.925V.

### Control Loop

During normal operation, the output voltage is sensed at FB pin by a resistive voltage divider and amplified through the error amplifier. The voltage of error amplifier output pin -- COMP is compared to the switch current to control the RS latch. At each cycle, the high side NMOS will be turned on when the oscillator sets the RS latch and turned off when current comparator resets the RS latch. When the load current increases, the FB pin voltage will drop below 0.925V, and it will cause the COMP voltage increasing until average inductor current arrives at new load current.

### Enable

The FR9886C  $\overline{\text{SHDN}}$  pin provides digital control to turn on/turn off the regulator. When the voltage of  $\overline{\text{SHDN}}$  exceeds the threshold voltage, the regulator will start the soft start function. If the  $\overline{\text{SHDN}}$  pin voltage is below the shutdown threshold voltage, the regulator will turn into shutdown mode and shutdown current will be smaller than 1μA. For auto start-up operation, connect  $\overline{\text{SHDN}}$  to VIN through a 100KΩ resistor.

### Soft Start

The FR9886C employs adjustable soft start function to reduce input inrush current during start up. When the device turns on, a 6μA current will begin to charge the capacitor which is connected from SS pin to GND. The equation for the soft start time is shown as below:

$$T_{SS}(\text{ms}) = \frac{C_{SS}(\text{nF}) \times V_{FB}}{I_{SS}(\mu\text{A})}$$

The  $V_{FB}$  voltage is 0.925V and the  $I_{SS}$  current is 6μA. If a 0.1μF capacitor is connected from SS pin to GND, the soft start time will be 15ms.

### Output Over Voltage Protection

When the FB pin voltage exceeds 1.5V, the output over voltage protection function will be triggered and turn off the high-side/low-side MOSFET.

### Input Under Voltage Lockout

When the FR9886C is power on, the internal circuits will be held inactive until  $V_{IN}$  voltage exceeds the input UVLO threshold voltage. And the regulator will be disabled when  $V_{IN}$  is below the input UVLO threshold voltage. The hysteresis of the UVLO comparator is 250mV (typ).

### Short Circuit Protection

The FR9886C provides short circuit protection function to prevent the device damage from short condition. When the short condition occurs and the feedback voltage drops lower than 0.4V, the oscillator frequency will be reduced to 110KHz to prevent the inductor current increasing beyond the current limit. In the meantime, the current limit will also be reduced to lower the short current. Once the short condition is removed, the frequency and current limit will return to normal.

### Over Current Protection

The FR9886C over current protection function is implemented by using cycle-by-cycle current limit architecture. The inductor current is monitored by measuring the high-side MOSFET series sense resistor voltage. When the load current increases, the inductor current will also increase. When the peak inductor current reaches the current limit threshold, the output voltage will start to drop. When the over current condition is removed, the output voltage will return to the regulated value.

### Over Temperature Protection

The FR9886C incorporates an over temperature protection circuit to protect itself from overheating. When the junction temperature exceeds the thermal shutdown threshold temperature, the regulator will be shutdown. And the hysteresis of the over temperature protection is 60°C (typ).

### Compensation

The stability of the feedback circuit is controlled by COMP pin. The compensation value of the application circuit is optimized for particular requirements. If different conversions are required, some of the components may need to be changed to ensure stability.

## Application Information

### Output Voltage Setting

The output voltage  $V_{OUT}$  is set by using a resistive divider from the output to FB. The FB pin regulated voltage is 0.925V. Thus the output voltage is:

$$V_{OUT} = 0.925V \times \left(1 + \frac{R1}{R2}\right)$$

Table 2 lists recommended values of R1 and R2 for most used output voltage.

**Table 2 Recommended Resistance Values**

$V_{OUT}$	R1	R2
5V	44.2k $\Omega$	10k $\Omega$
3.3V	26.1k $\Omega$	10k $\Omega$
2.5V	16.9k $\Omega$	10k $\Omega$
1.8V	9.53k $\Omega$	10k $\Omega$
1.2V	3k $\Omega$	10k $\Omega$

Place resistors R1 and R2 close to FB pin to prevent stray pickup.

### Input Capacitor Selection

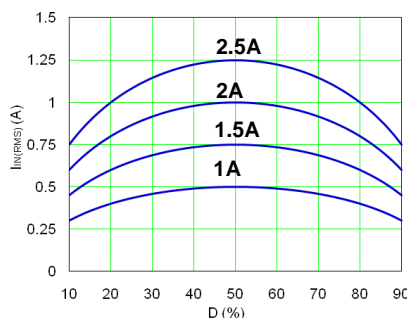
The use of the input capacitor is filtering the input voltage ripple and the MOSFETS switching spike voltage. Because the input current to the step-down converter is discontinuous, the input capacitor is required to supply the current to the converter to keep the DC input voltage. The capacitor voltage rating should be 1.25 to 1.5 times greater than the maximum input voltage. The input capacitor ripple current RMS value is calculated as:

$$I_{IN(RMS)} = I_{OUT} \times \sqrt{D \times (1-D)}$$

$$D = \frac{V_{OUT}}{V_{IN}}$$

Where D is the duty cycle of the power MOSFET.

This function reaches the maximum value at  $D=0.5$  and the equivalent RMS current is equal to  $I_{OUT}/2$ . The following diagram is the graphical representation of above equation.



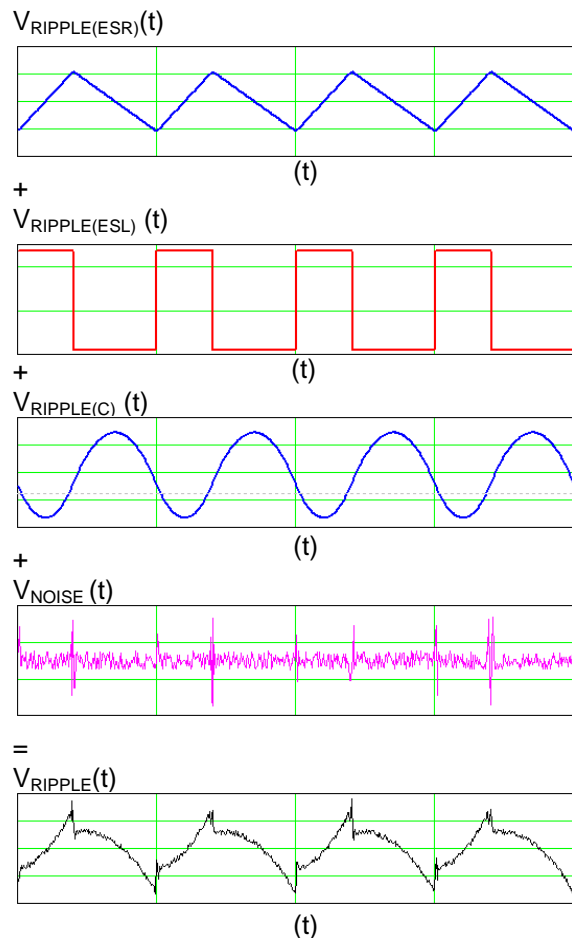
A low ESR capacitor is required to keep the noise minimum. Ceramic capacitors are better, but tantalum or low ESR electrolytic capacitors may also suffice. When using tantalum or electrolytic capacitors, a 0.1 $\mu$ F ceramic capacitor should be placed as close to the IC as possible.

### Output Capacitor Selection

The output capacitor is used to keep the DC output voltage and supply the load transient current. When operating in constant current mode, the output ripple is determined by four components:

$$V_{RIPPLE}(t) = V_{RIPPLE(C)}(t) + V_{RIPPLE(ESR)}(t) + V_{RIPPLE(ESL)}(t) + V_{NOISE}(t)$$

The following figures show the form of the ripple contributions.



**Application Information (Continued)**

$$V_{\text{RIPPLE(ESR, p-p)}} = \frac{V_{\text{OUT}}}{F_{\text{OSC}} \times L} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right) \times \text{ESR}$$

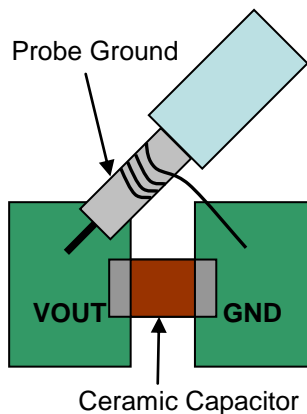
$$V_{\text{RIPPLE(ESL, p-p)}} = \frac{\text{ESL}}{L + \text{ESL}} \times V_{\text{IN}}$$

$$V_{\text{RIPPLE(C, p-p)}} = \frac{V_{\text{OUT}}}{8 \times F_{\text{OSC}}^2 \times L \times C_{\text{OUT}}} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right)$$

Where  $F_{\text{OSC}}$  is the switching frequency,  $L$  is the inductance value,  $V_{\text{IN}}$  is the input voltage, ESR is the equivalent series resistance value of the output capacitor, ESL is the equivalent series inductance value of the output capacitor and the  $C_{\text{OUT}}$  is the output capacitor.

Low ESR capacitors are preferred to use. Ceramic, tantalum or low ESR electrolytic capacitors can be used depending on the output ripple requirements. When using the ceramic capacitors, the ESL component is usually negligible.

It is important to use the proper method to eliminate high frequency noise when measuring the output ripple. The figure shows how to locate the probe across the capacitor when measuring output ripple. Removing the scope probe plastic jacket in order to expose the ground at the tip of the probe. It gives a very short connection from the probe ground to the capacitor and eliminates noise.



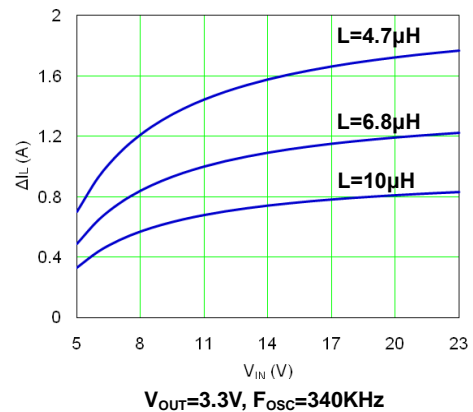
**Inductor Selection**

The output inductor is used for storing energy and filtering output ripple current. But the trade-off condition often happens between maximum energy storage and the physical size of the inductor. The first consideration for selecting the output inductor is to make sure that the inductance is large enough to keep the converter in the continuous current mode.

That will lower ripple current and result in lower output ripple voltage. The  $\Delta I_L$  is inductor peak-to-peak ripple current:

$$\Delta I = \frac{V_{\text{OUT}}}{F_{\text{OSC}} \times L} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right)$$

The following diagram is an example to graphical represent  $\Delta I_L$  equation.



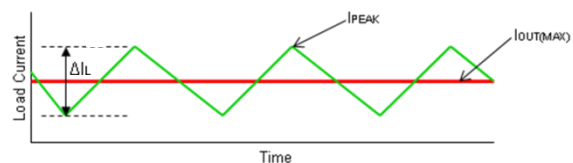
A good compromise value between size and efficiency is to set the peak-to-peak inductor ripple current  $\Delta I_L$  equal to 30% of the maximum load current. But setting the peak-to-peak inductor ripple current  $\Delta I_L$  between 20%~50% of the maximum load current is also acceptable. Then the inductance can be calculated with the following equation:

$$\Delta I = 0.3 \times I_{\text{OUT(MAX)}}$$

$$L = \frac{(V_{\text{IN}} - V_{\text{OUT}}) \times V_{\text{OUT}}}{V_{\text{IN}} \times F_{\text{OSC}} \times \Delta I_L}$$

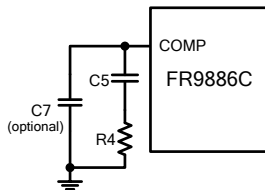
To guarantee sufficient output current, peak inductor current must be lower than the FR9886C high-side MOSFET current limit. The peak inductor current is as below:

$$I_{\text{PEAK}} = I_{\text{OUT(MAX)}} + \frac{\Delta I_L}{2}$$



## Application Information (Continued)

### Compensation Components Selection



Select the appropriate compensation value by following procedure:

1. Calculate the R4 value with the following equation:

$$R4 < \frac{2\pi \times C_{OUT} \times 0.1 \times F_{OSC} \times V_{OUT}}{G_{EA} \times G_{CS} \times V_{REF}}$$

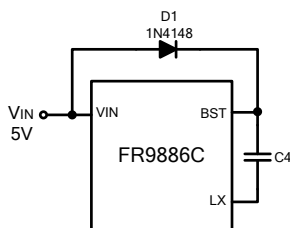
where  $G_{EA}$  is the error amplifier voltage gain, and  $G_{CS}$  is the current sense gain.

2. Calculate the C5 value with the following equation:

$$C5 > \frac{4}{2\pi \times R4 \times 0.1 \times F_{OSC}}$$

### External Diode Selection

For 5V input applications, it is recommended to add an external boost diode. This helps improving the efficiency. The boost diode can be a low cost one, such as 1N4148.



### PCB Layout Recommendation

The device's performance and stability are dramatically affected by PCB layout. It is recommended to follow these general guidelines shown as below:

1. Place the input capacitors and output capacitors as close to the device as possible. The traces which connect to these capacitors should be as short and wide as possible to minimize parasitic inductance and resistance.
2. Place feedback resistors close to the FB pin.
3. Keep the sensitive signal (FB) away from the switching signal (LX).

4. The exposed pad of the package should be soldered to an equivalent area of metal on the PCB. This area should connect to the GND plane and have multiple via connections to the back of the PCB as well as connections to intermediate PCB layers. The GND plane area connecting to the exposed pad should be maximized to improve thermal performance.
5. Multi-layer PCB design is recommended.

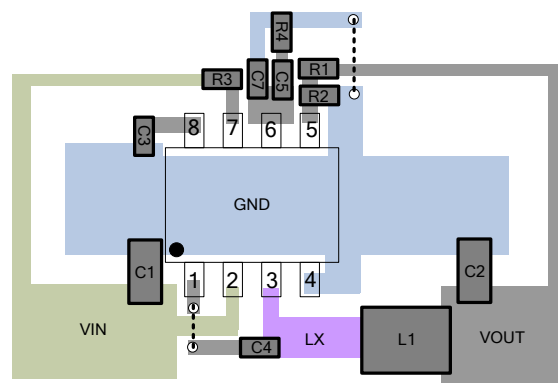


Figure 21. FR9886C Recommended Layout Diagram

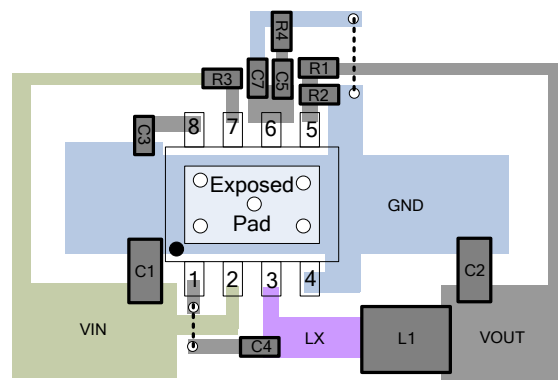
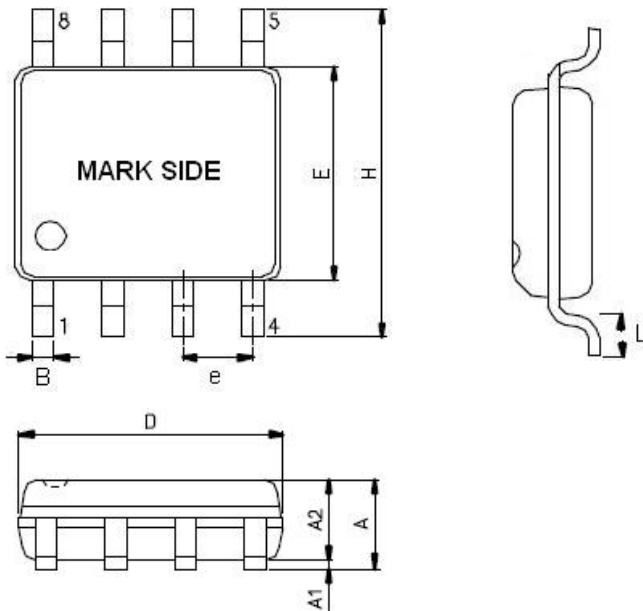


Figure 22. FR9886C Recommended Layout Diagram

**Outline Information**

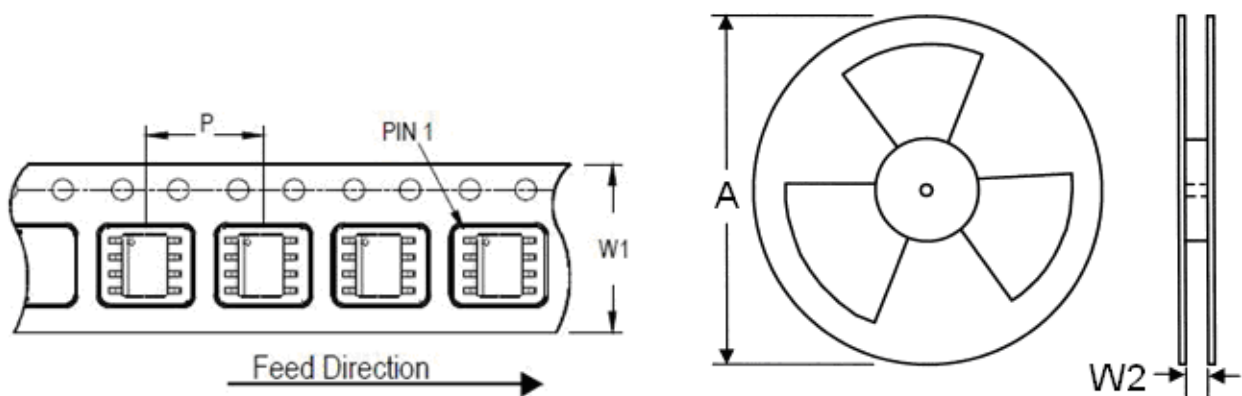
SOP-8 Package (Unit: mm)



SYMBOLS UNIT	DIMENSION IN MILLIMETER	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
A2	1.25	1.50
B	0.31	0.51
D	4.80	5.00
E	3.80	4.00
e	1.20	1.34
H	5.80	6.20
L	0.40	1.27

Note : Followed from JEDEC MO-012-E

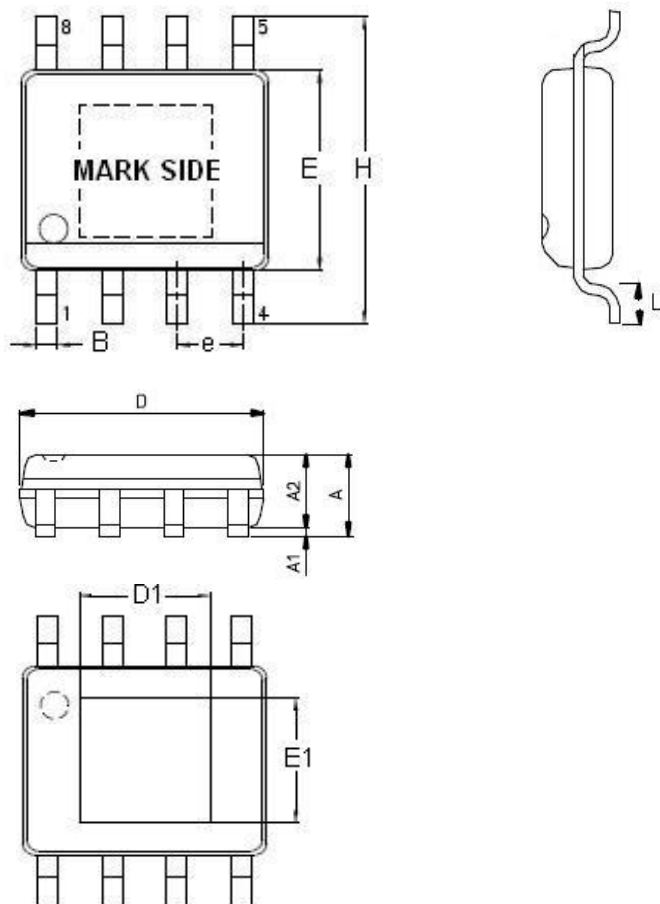
**Carrier Dimensions**



Tape Size (W1) mm	Pocket Pitch (P) mm	Reel Size (A)		Reel Width (W2) mm	Empty Cavity Length mm	Units per Reel
		in	mm			
12	8	13	330	12.4	400~1000	2,500

**Outline Information (Continued)**

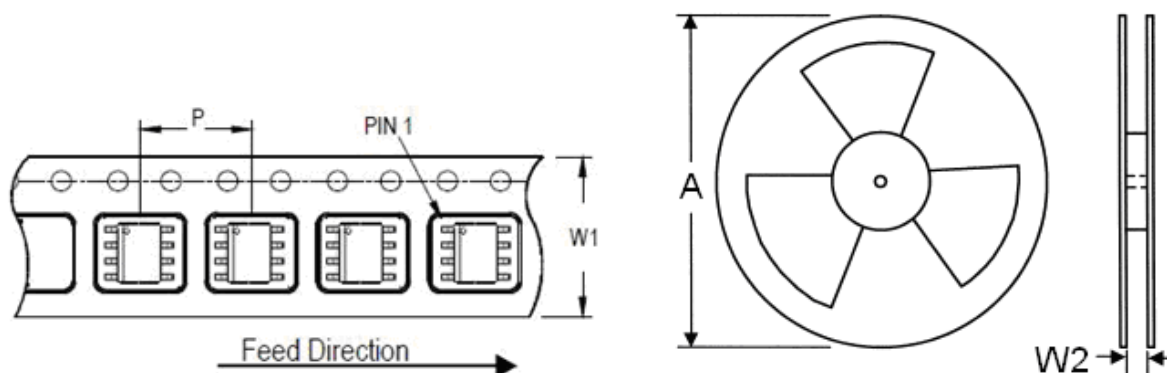
SOP-8 (Exposed Pad) Package (Unit: mm)



SYMBOLS UNIT	DIMENSION IN MILLIMETER	
	MIN	MAX
A	1.25	1.70
A1	0.00	0.15
A2	1.25	1.55
B	0.31	0.51
D	4.80	5.00
D1	3.04	3.50
E	3.80	4.00
E1	2.15	2.41
e	1.20	1.34
H	5.80	6.20
L	0.40	1.27

Note : Followed From JEDEC MO-012-E.

**Carrier Dimensions**



Tape Size (W1) mm	Pocket Pitch (P) mm	Reel Size (A)		Reel Width (W2) mm	Empty Cavity Length mm	Units per Reel
		in	mm			
12	8	13	330	12.4	400~1000	2,500

**Life Support Policy**

Fitipower's products are not authorized for use as critical components in life support devices or other medical systems.